

Wet Process Module and Method of Operation

Abstract

A wet process module (10), in particular a lacquering module, for the treatment
5 of substrates, in particular wafers, has a process chamber (12) comprising a
process pot (24) for treating the substrate, an air inlet (16) for supplying air into the
process chamber (12), at least one bypass outlet (38) and at least one process pot
outlet (36). The at least one bypass outlet (38) and the at least one process pot
outlet (36) are air outlets for discharging air out of the process chamber (12).
10 Furthermore, the at least one process pot outlet (36) is provided in the process pot
(24) and the at least one bypass outlet (38) is provided outside the process pot
(24). Furthermore, a method of operating such a wet process module (10) is
shown.

Figure 1